

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com

Product image



















High-temperature-resistant, 90° angled, open male header. Packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, open side, THT/THR solder connection, 5.00 mm, Number of poles: 14, 90°, Solder pin length (I): 3.2 mm, tinned, black, Box
Order No.	<u>1840010000</u>
Туре	SL-SMT 5.00HC/14/90 3.2SN BK BX
GTIN (EAN)	4032248350759
Qty.	50 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Вох

Creation date March 25, 2021 4:34:59 PM CET



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Technical data

Dimensions and weights

Depth	12 mm	Depth (inches)	0.472 inch
Height	11.7 mm	Height (inches)	0.461 inch
Height of lowest version	8.5 mm	Net weight	6.1 g
Width	70 mm	Width (inches)	2.756 inch

System specifications

Product family	OMNIMATE Signal - series	Type of connection	
	BL/SL 5.00		Board connection
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)	
	connection		5 mm
Pitch in inches (P)	0.197 inch	Outgoing elbow	90°
Number of poles	14	Number of solder pins per pole	1
Solder pin length (I)	3.2 mm	Solder pin length tolerance	+0.1 / -0.2 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,03 mm
Solder eyelet hole diameter (D)	1.5 mm	Solder eyelet hole diameter tolerance (D)+ 0,1 mm
L1 in mm	65 mm	L1 in inches	2.559 inch
Number of rows	1	Pin series quantity	1
Volume resistance	≤5 mΩ	Can be coded	Yes
Plugging force/pole, max.	7 N	Pulling force/pole, max.	5.5 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface		Layer structure of solder connection	13 μm Ni / 24 μm Sn
	tinned		matt
Layer structure of plug contact	13 μm Ni / 24 μm Sn	Storage temperature, min.	
	matt		-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2 4 kV		Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		



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Rated data acc. to CSA

nstitute (CSA)	€P ·	Certificate No. (CSA)	
			200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	15 A	Rated current (Use group D / CSA)	15 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	15 A	Rated current (Use group D / CSA)	15 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Rated data acc. to UL 1059			
Institute (UR)	<i>7</i> 7.	Certificate No. (UR)	E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	
Rated current (Use group B / UL 1059)	18.5 A	Rated current (Use group D / UL 1059)	
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Packing			
		VDE	40
Packaging	Box	VPE length	42 mm
VPE width	70 mm	VPE height	168 mm
Classifications			
ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 9.0 ECLASS 10.0	27-44-04-02	ECLASS 9.1 ECLASS 11.0	27-44-04-02
LCLA33 10.0	27-44-04-02	ECLASS 11.0	27-40-02-01
Important note			
IPC conformity	standards and norms and comp	eveloped, manufactured and delivered according oly with the assured properties in the data sheet Class 2". Further claims on the products can be e	resp. fulfill decorative properties
	in accordance with IFC-A-010	Ciass Z . Further claims on the products can be t	evaluated off fequest.

Classifications				
ETIM 6.0	EC002637	ETIM 7.0	EC002637	
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02	
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01	
Important note				
IPC conformity	standards and norms an	s are developed, manufactured and deliv d comply with the assured properties in A-610 "Class 2". Further claims on the pr	the data sheet resp. fulfill decorative properties	
Notes	Gold-plated contact si	Gold-plated contact surfaces on request		
	Rated current related to rated cross-section & min. No. of poles.			
	Diameter of solder eye	elet D = 1.4+0.1mm		
	Solder eyelet diamete	r D = 1.5 + 0.1 mm, from 9 poles		
	• P on drawing = pitch			
	•	to the component itself. Clearance and c lance with the relevant application stand	reepage distances to other components are to ards.	
	Long term storage of	the product with average temperature of	50 °C and average humidity 70%, 36 months	



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Technical data

Approvals

Approvals



ROHS	Conform
UL File Number Search	E60693

Downloads

Approval/Certificate/Document of	
Conformity	Declaration of the Manufacturer
Engineering Data	<u>STEP</u>



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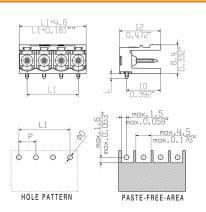
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Drawings

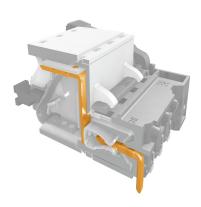
Product image



Dimensional drawing



Product benefits



Safe power transmission Proven properties



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Drawings

Product benefits





Recommended wave solderding profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.



Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- · Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.